IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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SERIAL NO.:

FILED:

Herewith

TITLE: METHOD FOR MANUFACTURING VERY LOW ROUGHNESS ELECTRODEPOSITED COPPER FOIL AND ELECTRODEPOSITED COPPER FOIL

MANUFACTURED THEREBY

PRELIMINARY AMENDMENT

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450

Sir:

In conjunction with the filing of the present application, and prior to an initial Official Action on this matter, please amend the above-identified application as follows:

Preliminary Amendment: SPECIFICATION AMENDMENTS

In Paragraph [0019], please amend the paragraph as follows:

The present invention will become better understood with reference to the accompanying drawings which are given only by way of illustration and thus are not limitative restrictive of the present invention, wherein;

In Paragraph [0020], please amend the paragraph as follows:

Figure 1 is a <u>schematic</u> view illustrating the construction of a copper manufacture apparatus for describing a method for manufacturing an electrodeposited copper foil according to the present invention; .

In Paragraph [0021], please amend the paragraph as follows:

Figure 2 is a picture obtained by photographing an electrodeposited copper foil manufactured according to an embodiment 1 of the present invention using a SEM; and.